

9/14/06

09-18-2006

Client Code: QCO.033A




:ET

To the Director, U.S. Patent and Trade

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ied original documents or copy thereof.

<p>1. Name of conveying party(ies): (List using letters or numbers for multiple parties)</p> <ol style="list-style-type: none"> 1. Teruo Sasagawa; 2. Clarence Chui 3. Manish Kothari 4. SuryaPrakash Ganti 5. Jeffrey B. Sampsell 6. Chun-Ming Wang <p>Additional name(s) of conveying party(ies) attached?</p> <p>() Yes (X) No</p>	<p>2. Name and address of receiving party(ies):</p> <p>Name: QUALCOMM MEMS Technologies, Inc.</p> <p>Internal Address: 5775 Morehouse Drive</p> <p>Street Address: same as above</p> <p>City: San Diego State: CA</p> <p>ZIP: 92121</p> <p>Additional name(s) of receiving party(ies) attached?</p> <p>() Yes (X) No</p>
<p>3. Nature of conveyance:</p> <p>(X) Assignment () Security Agreement</p> <p>() Merger () Change of Name</p> <p>() Other:</p> <p>Execution Date: (List as in section 1 if multiple signatures)</p> <ol style="list-style-type: none"> 1. August 18, 2006 2. August 18, 2006 3. August 29, 2006 4. August 18, 2006 5. August 18, 2006 6. August 18, 2006 	<p>4. US or PCT Application number(s) or US Patent number(s):</p> <p>(X) Patent Application No.: 11/491,389</p> <p>Filing Date: July 21, 2006</p> <p>Additional numbers attached?</p> <p>() Yes (X) No</p>
<p>5. Party to whom correspondence concerning document should be mailed:</p> <p>Customer No. 59,747</p> <p>Address: Knobbe, Martens, Olson & Bear, LLP 2040 Main Street, 14th Floor Irvine, CA 92614</p> <p>Return Fax: (949) 760-9502</p> <p>Attorney's Docket No.: QCO.033A</p>	<p>6. Total number of applications and patents involved: 1</p> <p>OFFICE OF PUBLIC RECORDS SEP 14 PM 2:35 FINANCE SECTION</p>
<p>7. Total fee (37 CFR 1.21(h)): \$40</p> <p>(X) Enclosed</p>	<p>8. Deposit account number: 11-1410</p> <p>Please charge this account for any additional fees which may be required, or credit any overpayment to this account.</p>
<p>9. Statement and signature.</p> <p>To the best of my knowledge and belief, the foregoing information is true and correct, and any attached copy is a true copy of the original document.</p> <p><u>Tina Chen</u> Name of Person Signing</p> <p><u></u> Signature</p> <p><u>9/11/06</u> Date</p> <p>44,606 Registration No.</p> <p>Total number of pages including cover sheet, attachments and document: 5</p>	

Documents transmitted via Mail to be recorded with required cover sheet information to:

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PATENT
REEL: 018311 FRAME: 0047

ASSIGNMENT

WHEREAS, We, Teruo Sasagawa, a Japanese citizen, residing at 16345 Los Gatos Blvd., #18 Los Gatos, CA 95032, Clarence Chui, a U.S. citizen, residing at 1954 Los Altos Drive, San Mateo, CA 94402, Manish Kothari, a U.S. citizen, residing at 22460 Palm Avenue, Cupertino, CA 95014, SuryaPrakash Ganti, an Indian citizen, residing at 1839 Fallen Leaf Lane, Los Altos, CA 94024, Jeffrey B. Sampsell, a U.S. citizen, residing at 190 Ryland St., #4202, San Jose, CA 95110, and Chun-Ming Wang, a Taiwanese citizen, residing at 41730 Marigold Dr., Fremont, CA 94539, have invented certain new and useful improvements in a SUPPORT STRUCTURE FOR MEMS DEVICE AND METHODS THEREFOR for which we have caused to be filed an application for Letters Patent in the United States, Application No. 11/491,389, Filed on July 21, 2006;

AND WHEREAS, QUALCOMM MEMS Technologies, Inc. (hereinafter "ASSIGNEE"), a Delaware corporation, with its principal place of business at 5775 Morehouse Drive, San Diego, California 92121, U.S.A, desires to acquire the entire right, title, and interest in and to the said improvements and the said Application.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, we, the said inventors, do hereby acknowledge that we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, the entire right, title, and interest throughout the world in, to and under the said improvements, and the said application and all provisional application(s) to which said Application claims, or is entitled to claim, priority, and all divisions, renewals and continuations thereof, and all Letters Patent of the United States which may be granted thereon and all reissues and extensions thereof, and all rights of priority under International Conventions and applications for Letters Patent which may hereafter be filed for said improvements in any country or countries foreign to the United States, and all Letters Patent which may be granted for said improvements in any country or countries foreign to the United States and all extensions, renewals and reissues thereof; and we hereby authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said improvements to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE DO HEREBY sell, assign, transfer, and convey to the said ASSIGNEE, its successors, legal representatives, and assigns all claims for damages and all remedies arising out of any violation of the rights assigned hereby that may have accrued prior to the date of assignment to the said ASSIGNEE, or may accrue hereafter, including, but not limited to, the right to sue for, collect, and retain damages for past infringements of the said Letters Patent before or after issuance.

AND WE HEREBY covenant and agree that we will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known to us respecting said improvements, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said improvements in all countries.

IN TESTIMONY WHEREOF, I hereunto set my hand and seal this 18 day of Aug, 2006

Teruo Sasagawa
Teruo Sasagawa

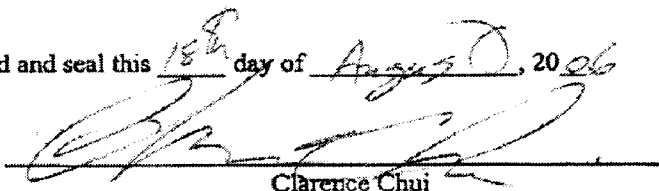
IN TESTIMONY WHEREOF, acknowledged by QUALCOMM MEMS TECHNOLOGIES, INC. this ____ day of _____, 20__.

QUALCOMM MEMS Technologies, Inc.

Name:
Title:

051008

IN TESTIMONY WHEREOF, I hereunto set my hand and seal this 18th day of August, 2006


Clarence Chui

IN TESTIMONY WHEREOF, acknowledged by QUALCOMM MEMS TECHNOLOGIES, INC. this ____ day
of _____, 20__.

QUALCOMM MEMS Technologies, Inc.

Name:
Title:

IN TESTIMONY WHEREOF, I hereunto set my hand and seal this 29 day of Aug, 2006.


Manish Kothari

IN TESTIMONY WHEREOF, acknowledged by QUALCOMM MEMS TECHNOLOGIES, INC. this ____ day
of _____, 20__.

QUALCOMM MEMS Technologies, Inc.

Name:
Title:

IN TESTIMONY WHEREOF, I hereunto set my hand and seal this 18 day of August, 2006


SuryaPrakash Ganti

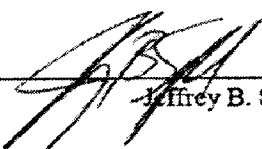
IN TESTIMONY WHEREOF, acknowledged by QUALCOMM MEMS TECHNOLOGIES, INC. this ____ day
of _____, 20__.

QUALCOMM MEMS Technologies, Inc.

Name:
Title:

051008

IN TESTIMONY WHEREOF, I hereunto set my hand and seal this 18th day of August, 2006




Jeffrey B. Sampsell

IN TESTIMONY WHEREOF, acknowledged by QUALCOMM MEMS TECHNOLOGIES, INC. this ____ day
of _____, 20__.

QUALCOMM MEMS Technologies, Inc.

Name:
Title:

IN TESTIMONY WHEREOF, I hereunto set my hand and seal this 18th day of August, 2006



Chun-Ming Wang

IN TESTIMONY WHEREOF, acknowledged by QUALCOMM MEMS TECHNOLOGIES, INC. this ____ day
of _____, 20__.

QUALCOMM MEMS Technologies, Inc.

Name:
Title:

ASSIGN1
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